

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Bor-Doou Rong	01/06/2015
Weng-Dah Ken	01/06/2015
RECEIVING PARTY DATA	
Name:	Etron Technology, Inc.
Street Address:	No. 6, Technology Road 5
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State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14599999
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SIGNATURE:	/STEFFI CHANG/
DATE SIGNED:	01/19/2015
Total Attachments: 2	
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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Bor-Dooou Rong Nationality: TW

Name: Weng-Dah Ken Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Etron Technology, Inc.

Address: No. 6, Technology Road 5, Hsinchu 30078, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"SYSTEM-IN-PACKAGE MODULE AND MANUFACTURE METHOD FOR A
SYSTEM-IN-PACKAGE MODULE"

Which is found in :

- (a) + U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____
(e) _____ International application no. _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this JAN 06 2015 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Bor-Doou Rong

Weng-Dah Ken

Signature of INVENTOR

Bor-Doou Rong

Weng-Dah Ken